

7. (Amended) A tiedown structure comprising:

a semiconductor substrate having a chip formed thereon;

an edge seal along an outer perimeter of the chip; and

a conductive connector forming an electrical connection between the edge seal and a portion of the chip.

10. (Amended) A method for forming a tiedown structure, comprising:

forming a device on a chip;

defining a kerf proximate the chip; and

forming an electrically conductive connector, the conductive connector connecting the device and the kerf.

17. (Once Amended) A method for forming a tiedown structure, comprising:

forming a chip on a semiconductor substrate, the chip including a device;

forming an edge seal along an outer perimeter of the chip; and

forming an electrically conductive connector, the conductive connector connecting the edge seal and the device.--